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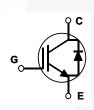
November 2013

FGA15N120ANTDTU 1200 V, 15 A NPT Trench IGBT

Features

- NPT Trench Technology, Positive temperature coefficient
- Low Saturation Voltage: V_{CE(sat), typ} = 1.9 V @ $I_C = 15$ A and $T_C = 25^{\circ}C$
- + Low Switching Loss: $E_{off, \ typ}$ = 0.6 mJ @ I_C = 15 A and T_C = 25°C
- Extremely Enhanced Avalanche Capability





cation such as induction heating, microwave oven.

Description

easy parallel operation.

Absolute Maximum Ratings

Symbol	Description		Ratings	Unit	
V _{CES}	Collector-Emitter Voltage		1200	V	
V _{GES}	Gate-Emitter Voltage		± 20	V	
I _C	Collector Current	@ $T_{C} = 25^{\circ}C$	30	A	
	Collector Current	@ T _C = 100°C	15	A	
I _{CM}	Pulsed Collector Current (Note 1)		45	A	
I _F	Diode Continuous Forward Current	@ T _C = 25°C	30	A	
	Diode Continuous Forward Current	@ T _C = 100°C	15	A	
I _{FM}	Diode Maximum Forward Current		45	A	
P _D	Maximum Power Dissipation	@ $T_{C} = 25^{\circ}C$	186	W	
	Maximum Power Dissipation	@ T _C = 100°C	74	W	
TJ	Operating Junction Temperature		-55 to +150	°C	
T _{stg}	Storage Temperature Range		-55 to +150	°C	
TL	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds		300	°C	

Thermal Characteristics

Symbol	ymbol Parameter		Max.	Unit
$R_{ ext{ heta}JC}$	Thermal Resistance, Junction-to-Case for IGBT		0.67	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case for Diode		2.88	°C/W
R_{\thetaJA}	P _{0JA} Thermal Resistance, Junction-to-Ambient		40	°C/W

Notes:

(1) Repetitive rating: Pulse width limited by max. junction temperature

FGA15N120ANTDTU — 1200 V, 15 A NPT Trench IGBT

Part Number Top Mark FGA15N120ANTDTU_F109 FGA15N120ANTDTU		Top Mark	Package Packing Method		Reel Size	Tape Width		Quantity
		FGA15N120ANTDTU	TO-3P	Tube	N/A	N/A		30
Electric	al Characte	eristics of the I		² C unless otherwise note	d	1		
Symbol	1	arameter		t Conditions	Min.	Тур.	Max	Unit
Off Charac	teristics							
ICES	Collector Cut-Of	f Current	$V_{CE} = V_{CES}, V_{GE} = 0 V$				3	mA
I _{GES}	G-E Leakage Current		$V_{GE} = V_{GES}, V_{CE} = 0 V$				± 250	nA
							•	
On Charac		· · ·				0.7		
V _{GE(th)}	G-E Threshold \			$V_{CE} = V_{GE}$	4.5	6.5	8.5	V
V _{CE(sat)}	Collector to Emitter Saturation Voltage		I _C = 15 A, V _{GE} = 15 V			1.9	2.4	V
			$I_{C} = 15 \text{ A}, V_{GE} = 15 \text{ V},$ $T_{C} = 125^{\circ}\text{C}$			2.2		V
			I _C = 30 A,	V _{GE} = 15 V		2.3		V
Dvnamic C	haracteristics							
C _{ies}		nput Capacitance $V_{CE} = 30 \text{ V}, \text{ V}_{GE} = 0 \text{ V},$			2650		pF	
C _{oes}	Output Capacita	nce	f = 1 MHz			143		pF
C _{res}	Reverse Transfe		-			96		pF
_	g Characteristics Turn-On Delay Time		V - 600	V _{CC} = 600 V, I _C = 15 A,		15		
t _{d(on)}	Rise Time	inte	$R_{G} = 10 \Omega, V_{GE} = 15 V,$ Inductive Load, $T_{C} = 25^{\circ}C$			-		ns
t _r		imo				20 160		ns
t _{d(off)}	Turn-Off Delay T Fall Time	Inte				100	180	ns
t _f	Turn-On Switchi		_			3		ns
E _{on}			_			0.6	4.5 0.9	mJ mJ
E _{off}	Turn-Off Switchi	5						
E _{ts}	Total Switching I Turn-On Delay 1		$V_{CC} = 600 \text{ V}, \text{ I}_{C} = 15 \text{ A},$ $R_{G} = 10 \Omega, \text{ V}_{GE} = 15 \text{ V},$ Inductive Load, T _C = 125°C			3.6 15	5.4	mJ
t _{d(on)}	Rise Time					20		ns
t _r	Turn-Off Delay T	ïme				170		ns
t _{d(off)}	Fall Time	inte				150		ns
t _f E _{on}	Turn-On Switchi	naloss				3.2	4.8	mJ
	Turn-Off Switchi	-				0.8	1.2	mJ
E _{off} E _{ts}	Total Switching I	•				4.0	6.0	mJ
	Total Gate Charg		Ve= = 600	V = 15		4.0	180	nC
Qg			$V_{CE} = 600 \text{ V}, \text{ I}_{C} = 15 \text{ A},$ $V_{GE} = 15 \text{ V}$					
Q _{ge}	Gate-Emitter Ch	orao	$V_{GF} = 10$ V			16	22	nC

Symbol V _{FM}	Parameter	Test Conditions		Min.	Тур.	Max.	Unit
	Diode Forward Voltage	I _F = 15 A	$T_{C} = 25^{\circ}C$		1.7	2.7	V
			T _C = 125°C		1.8		
rr Diode Reverse	Diode Reverse Recovery Time	I _F = 15 A di _F /dt = 200 A/μs	$T_{C} = 25^{\circ}C$		210	330	ns
			T _C = 125°C		280		
I _{rr} Diode Peak Reverse Recovery rent	Diode Peak Reverse Recovery Cur-		$T_{C} = 25^{\circ}C$		27	40	А
	rent		T _C = 125°C		31		
Q _{rr}	Diode Reverse Recovery Charge		$T_{\rm C} = 25^{\circ}{\rm C}$		2835	6600	nC
			T _C = 125°C		4340		

FGA15N120ANTDTU — 1200 V, 15 A NPT Trench IGBT

Typical Performance Characteristics

Figure 1. Typical Output Characteristics

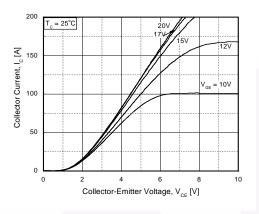


Figure 2. Typical Saturation Voltage Characteristics

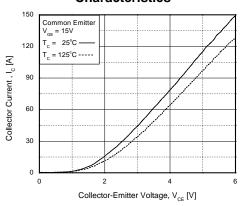


Figure 3. Saturation Voltage vs. Case Temperature at Variant Current Level

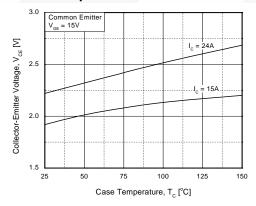


Figure 5. Saturation Voltage vs. V_{GE}

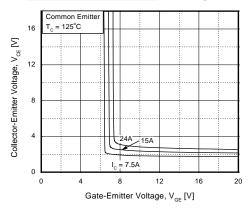


Figure 4. Saturation Voltage vs. V_{GE}

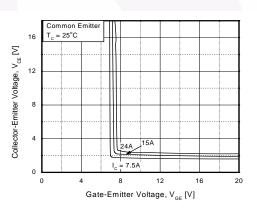
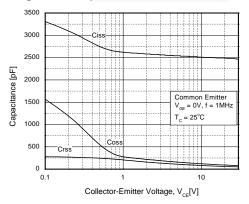


Figure 6. Capacitance Characteristics



FGA15N120ANTDTU — 1200 V, 15 A NPT Trench IGBT

Typical Performance Characteristics (Continued)

Figure 7. Turn-On Characteristics vs. Gate Resistance

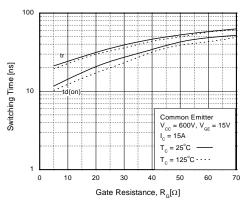


Figure 8. Turn-Off Characteristics vs. Gate Resistance

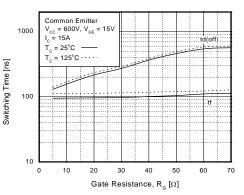
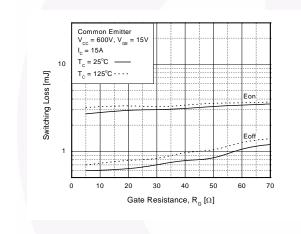
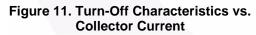


Figure 9. Switching Loss vs. Gate Resistance





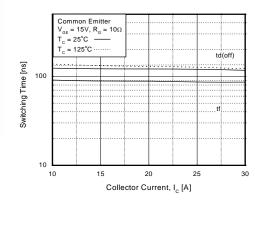


Figure 10. Turn-On Characteristics vs. Collector Current

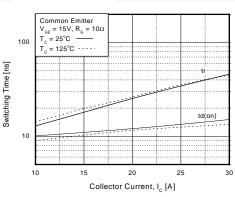
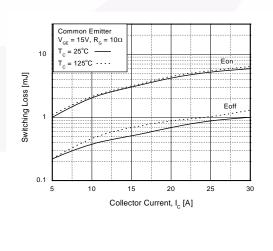
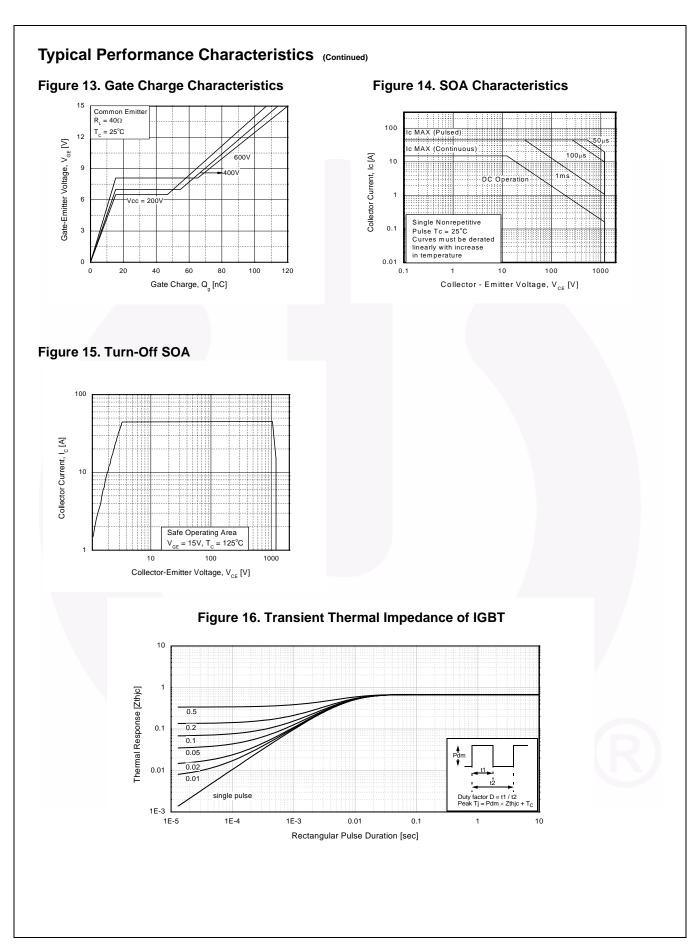
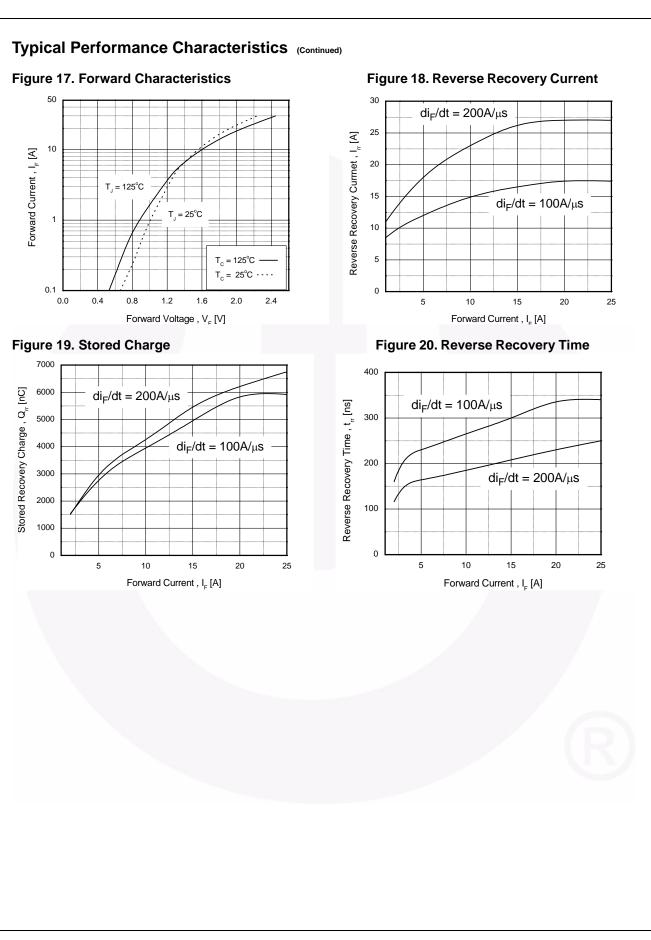


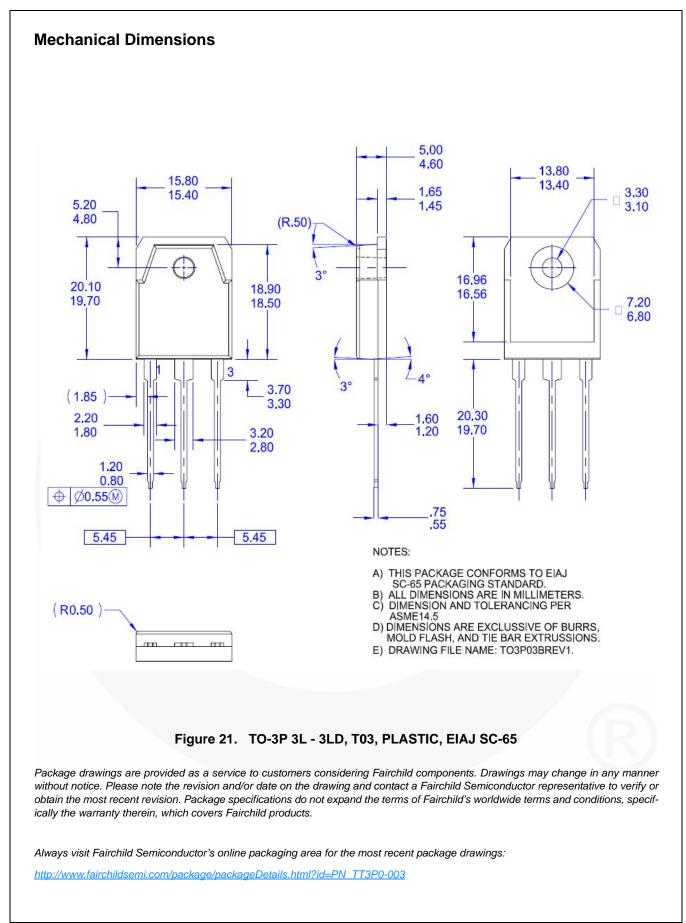
Figure 12. Switching Loss vs. Collector Current



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